

• General Description

The AGM55P10S combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{\text{DS(ON)}}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- ■Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

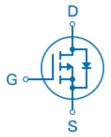
BVDSS	RDSON	ID
-100V	65mΩ	-12A

SOP8 Pin Configuration

Top View







Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM55P10S	AGM55P10S	SOP8	330mm	12mm	3000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	-100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
lD	Drain Current-Continuous(Tc=25℃) (Note 1)	-12	А
טו	Drain Current-Continuous(Tc=100℃)	-8.0	Α
IDM (pluse)	Drain Current-Pulsed (Note 2)	-48	Α
	Maximum Power Dissipation(Tc=25℃)	2.5	W
PD	Maximum Power Dissipation(Tc=100℃)	1.0	W
EAS	Avalanche energy (Note 3)	195	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹		50	°C/W



Table 3. Electrical Characteristics (TJ=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off Sta	ates					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=-250µA	-100			V
IDSS	Zero Gate Voltage Drain Current	VDS=-100V,VGS=0V			-1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=-250μA	-1.2	-1.8	-2.2	V
gFS	Forward Transconductance	VDS=-5V,ID=-5A		13		S
RDS(on)	Drain-Source On-State Resistance	VGS=-10V, ID=-10A		65	70	mΩ
		VGS=-4.5V, ID=-5A		71	75	mΩ
Dynamic (Characteristics					
Ciss	Input Capacitance	VDS=-50V,VGS=0V,		4507		pF
Coss	Output Capacitance	F=1MHZ		97		pF
Crss	Reverse Transfer Capacitance			15		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz				Ω
Switching	Times					
td(on)	Turn-on Delay Time			49		nS
tr	Turn-on Rise Time	VGS=-10V,VDS=-50V,		71		nS
td(off)	Turn-Off Delay Time	ID=-10A,RGEN=4.5Ω		555		nS
tf	Turn-Off Fall Time			187		nS
Qg	Total Gate Charge			773	-	nC
Qgs	Gate-Source Charge	VGS=-10V, VDS=-50V, ID=-10A		17	-	nC
Qgd	Gate-Drain Charge	750 000, 15 10,0		9.1		nC
Source-Dr	rain Diode Characteristics					
ISD	Source-Drain Current(Body Diode)				-12	Α
VSD	Forward on Voltage	VGS=0V,IS=-10A			-1.2	V
trr	Reverse Recovery Time	Isd=-10A ,		32		ns
Qrr	Reverse Recovery Charge	dl/dt=100A/µs , TJ=25℃		49		nc

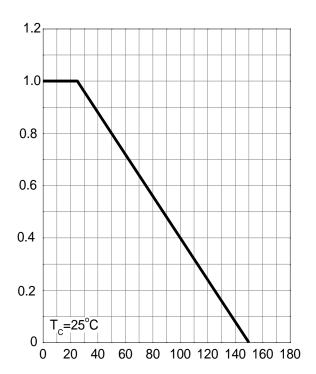
Notes 1. The maximum current rating is package limited.

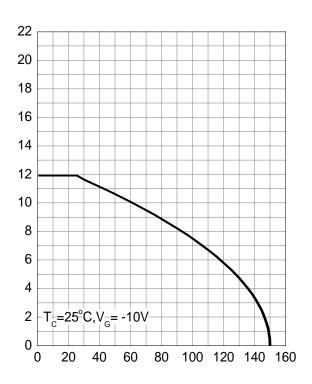
Notes 2. Repetitive Rating: Pulse width limited by maximum junction temperature

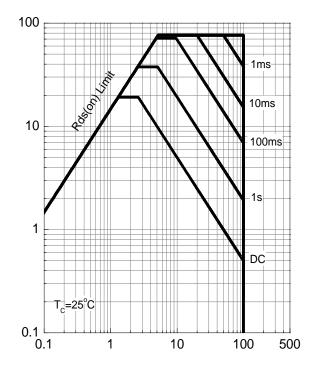
Notes 3.EAS condition: TJ=25℃

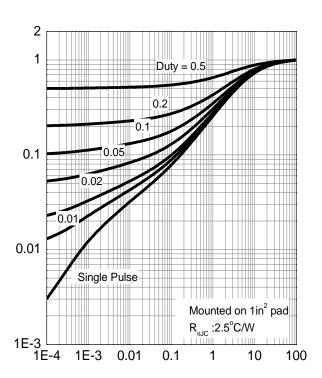


Typical Characteristics



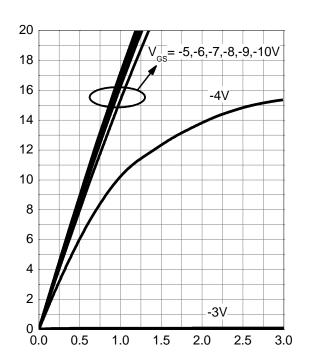


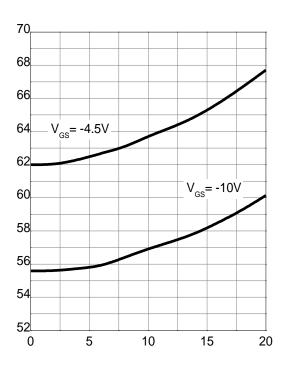


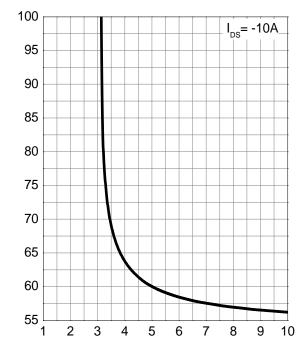


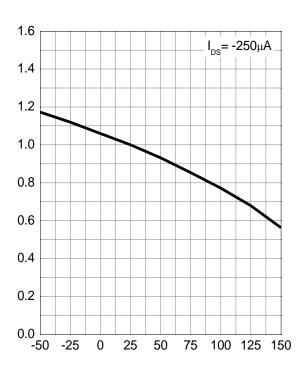


Typical Characteristics (cont.)



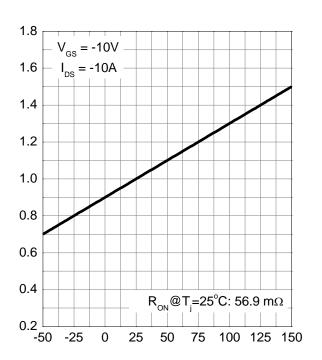


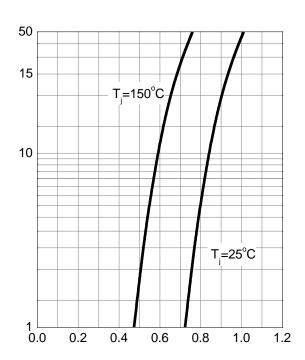


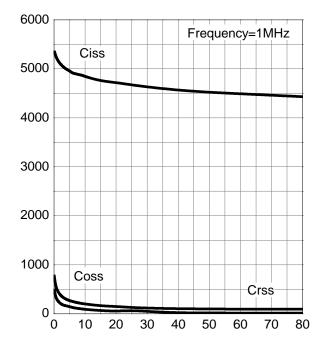


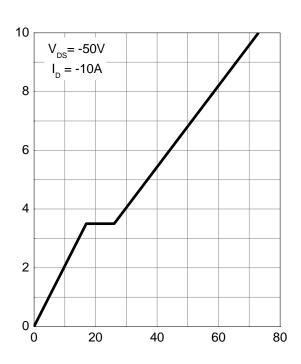


Typical Characteristics (cont.)



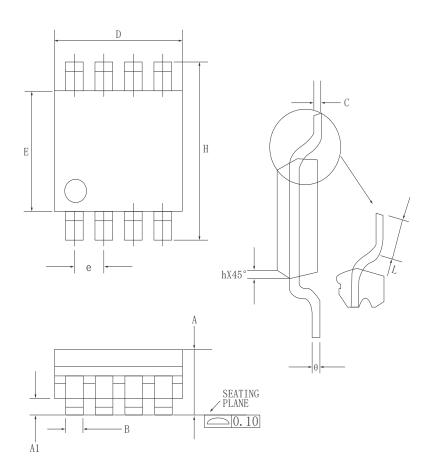




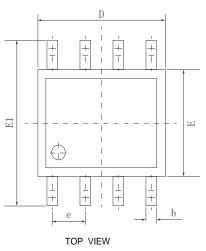


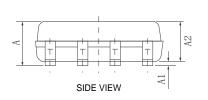


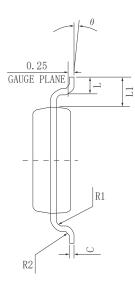
•Dimensions (SOP8)



DTM	MILLIMETERRS		
DIM	MIN	MAX	
A	1. 35	1.75	
A1	0.02	0.15	
В	0.33	0.5	
С	0.1	0. 25	
D	4.8	5	
Е	3.8	4	
е	1. 27 (BSC)		
Н	5.8	6. 2	
h	0. 25	0.5	
I	0.4	1. 25	
θ	0°	7°	





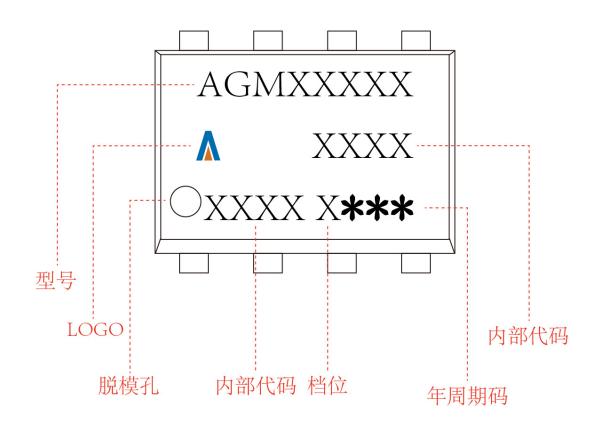


SIDE VIEW

	I	T	
SYMBOL	MIN NOM		MAX
A	1.40	1.40 1.60	
A1	0.05	0.15	0.25
A2	1. 35	1.45	1.55
b	0.30	0.40	0.50
С	0. 153	0. 203	0. 253
D	4.80	4.80 4.90	
Е	3. 80	3. 80 3. 90	
E1	5. 80 6. 00		6. 20
L	0.45	0.70	1.00
θ	2° 4°		6°
L1	1.04 REF		
е	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		



SOP8
Marking Instructions:





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